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DATA SHEET

PART NO. : L-C155LBJEECT-HD

REV : A/2

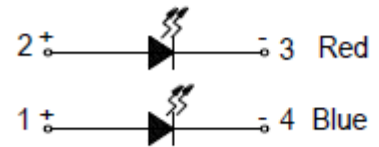
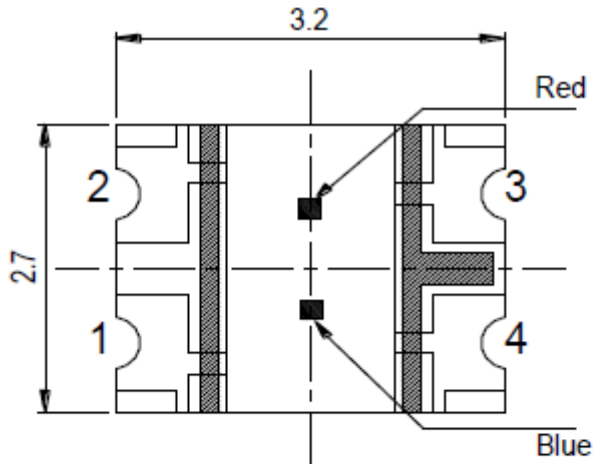
CUSTOMER'S APPROVAL : _____ DCC : _____

DRAWING NO. : DS-51-17-061

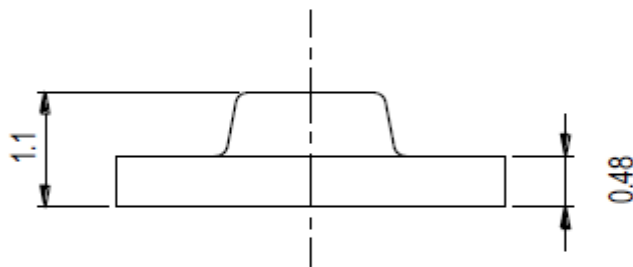
DATE : 2021-11-19

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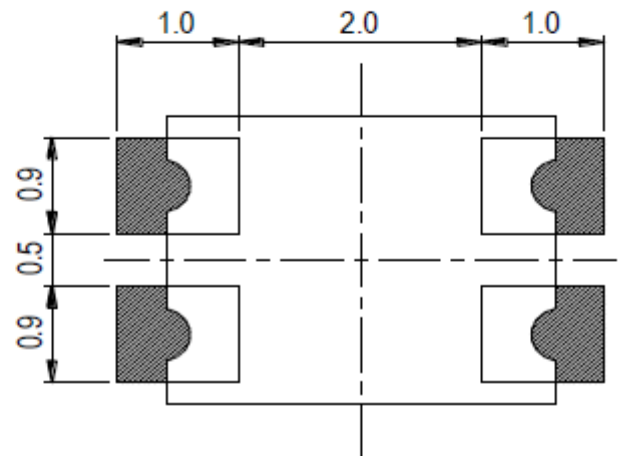
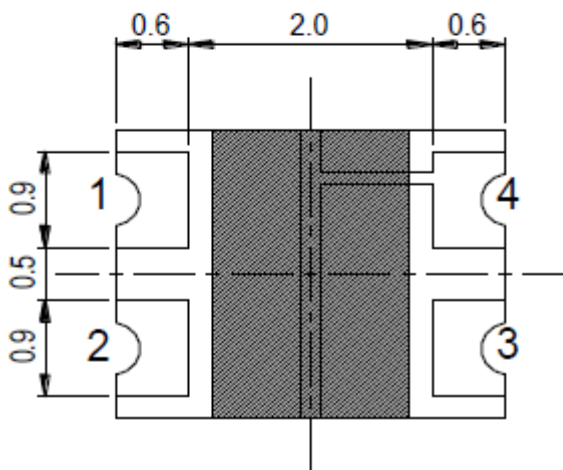
PACKAGE DIMENSIONS



Polarity



Recommended Solder Pad



Note:
Tolerance unless mentioned is ± 0.1 mm, Unit = mm



3.2*2.7*1.1 mm SMD LED

L-C155LBJEECT-HD

REV:A/2

FEATURES

- * 3.2*2.7*1.1 mm SMD LED
- * Top view LED
- * Compatible with infrared and vapor phase reflow solder process
- * Wide viewing angle

CHIP MATERIALS

- * Dice Material : InGaN / AlInGaP
- * Light Color : Blue & Red
- * Lens Color : WATER CLEAR

ABSOLUTE MAXIMUM RATING : (Ta = 25°C)

SYMBOL	PARAMETER	RATING		UNIT
		LB	JE	
PD	Power Dissipation	95	60	mW
If	Forward Current	25		mA
Ifp	Peak Forward Current (1/10 duty cycle 0.1ms)	100	60	mA
ESD	Electrostatic Discharge Threshold(HBM)	2000	2000	V
Topr	Operating Temperature Range	-30°C ~85°C		°C
Tstg	Storage Temperature Range	-40°C ~100°C		°C
Tsol	Soldering Temperature	Reflow Soldering 260°C For 10 SEC Hand Soldering 350°C For 3 SEC		

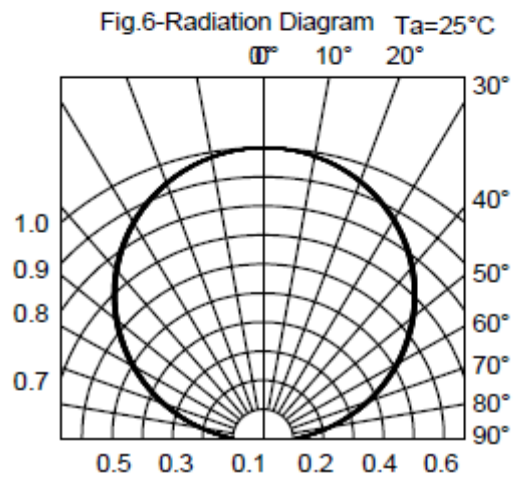
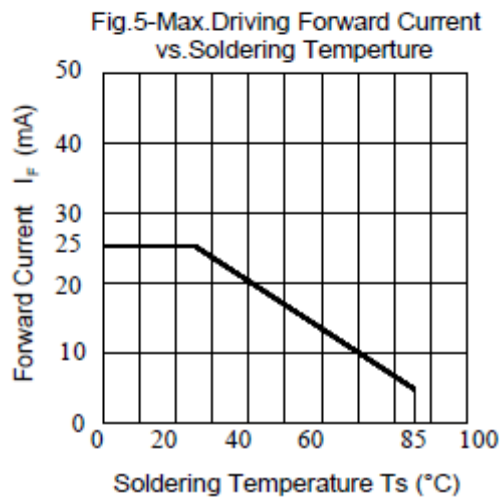
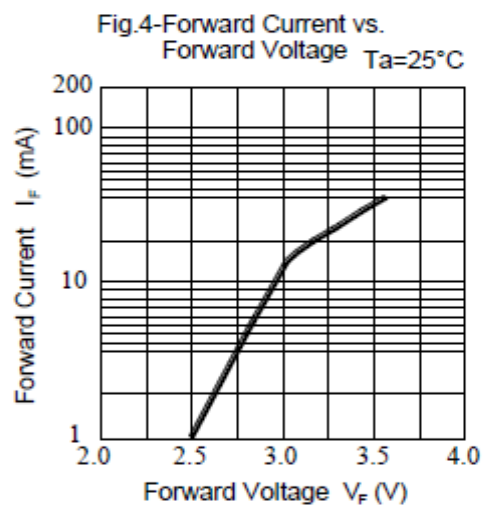
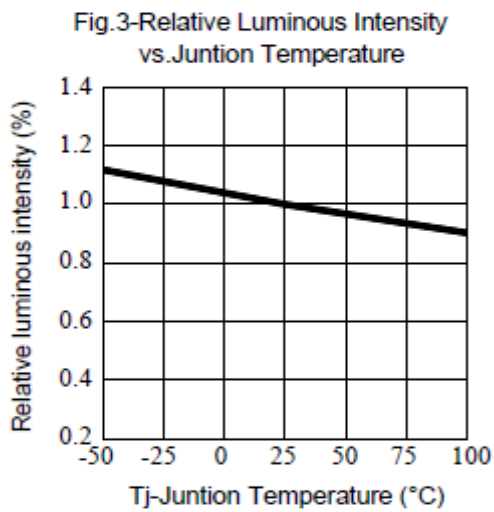
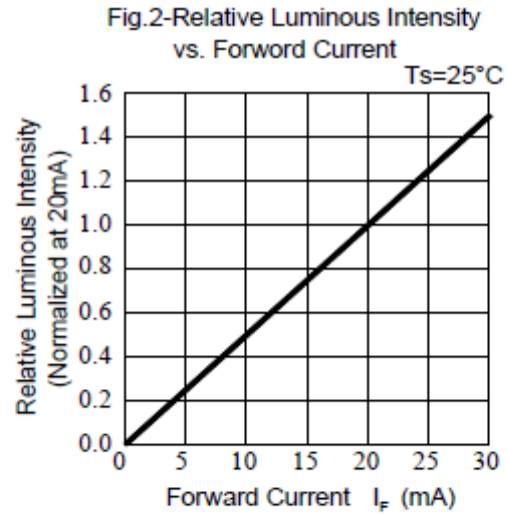
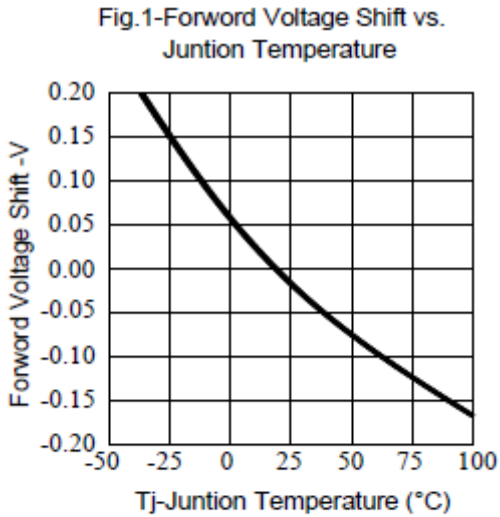
ELECTRO-OPTICAL CHARACTERISTICS : (Ta = 25°C)

SYMBOL	PARAMETER	TEST CONDITION	VALUE			UNIT	
			MIN.	TYP.	MAX.		
VF	Forward Voltage	IF = 20mA	LB	2.7	3.1	3.5	V
			JE	1.7	2.1	2.4	
IR	Reverse Current	VR = 5V	--	--	10	µA	
λD	Dominant Wavelength	IF = 20mA	LB	460	468	475	nm
			JE	615	624	635	
2θ1/2	Half Intensity Angle	IF = 20mA	--	120	--	deg	
Iv	Luminous Intensity	IF = 20mA	LB	112	200	285	mcd
			JE	112	200	285	

Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

Blue:



Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

Red:

Fig.1-Forward Voltage Shift vs. Junction Temperature

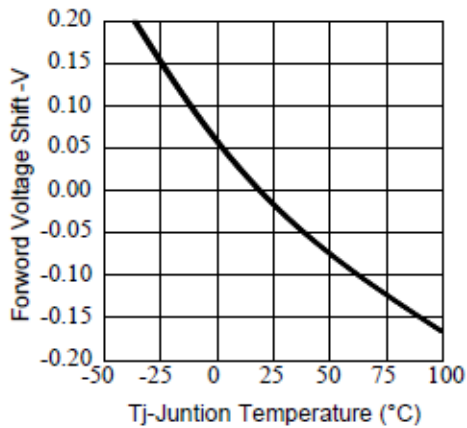


Fig.2-Relative Luminous Intensity vs. Forward Current Ts=25°C

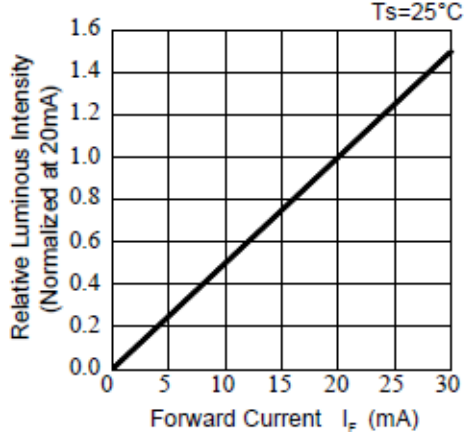


Fig.3-Relative Luminous Intensity vs. Junction Temperature

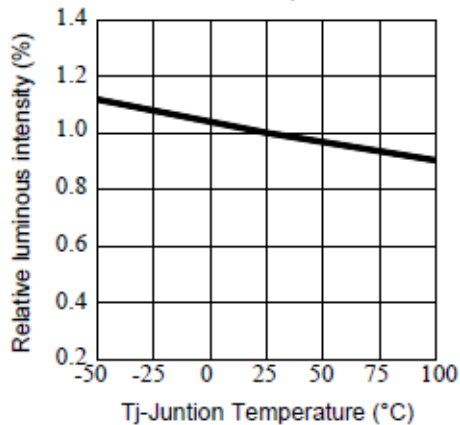


Fig.4-Forward Current vs. Forward Voltage Ta=25°C

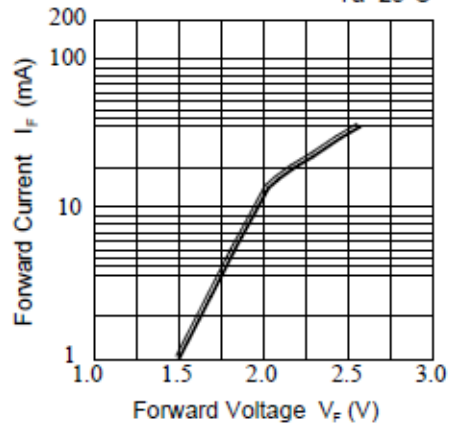


Fig.5-Max. Driving Forward Current vs. Soldering Temperature

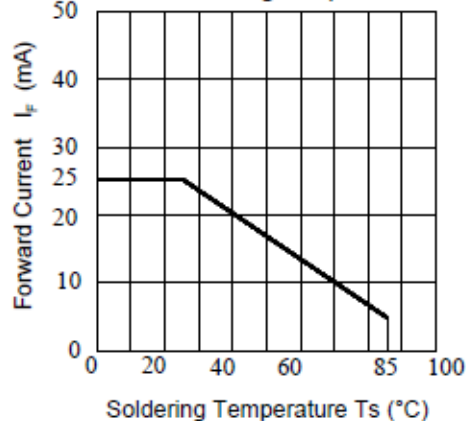
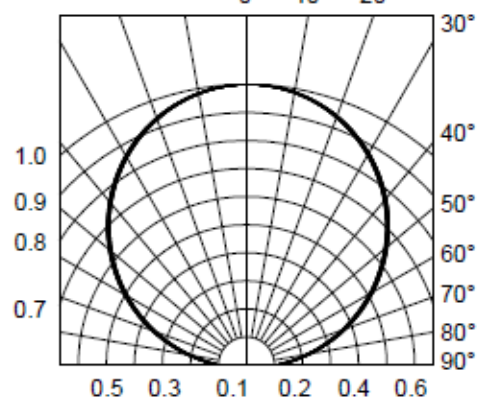


Fig.6-Radiation Diagram Ta=25°C





3.2*2.7*1.1 mm SMD LED

L-C155LBJEECT-HD

REV:A/2

Bin Code Description

Bin Range of Luminous Intensity (LB)

Bin Code	Min.	Max.	Unit	Condition
R	112	180	mcd	I _f =20mA
S	180	285		

Bin Range of Luminous Intensity(JE)

Bin Code	Min.	Max.	Unit	Condition
R	112	180	mcd	I _f =20mA
S	180	285		

Note:

Tolerance of Luminous Intensity: ±10%.

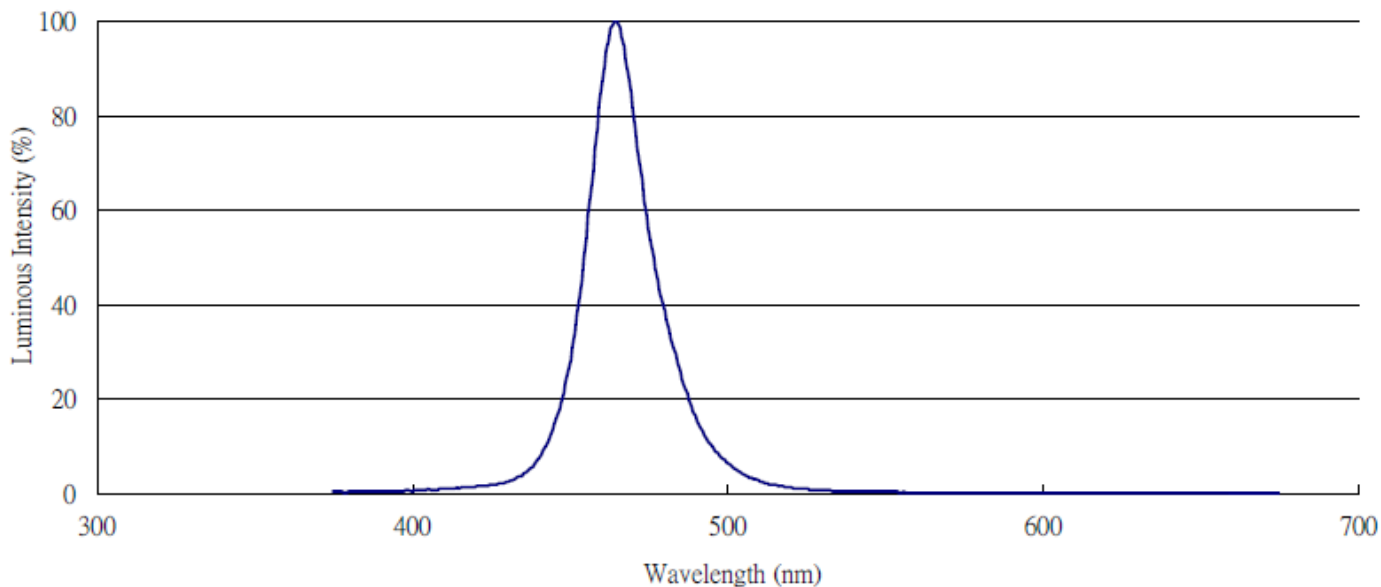
Bin Range of Dominant Wavelength(LB)

Bin Code	Min.	Max.	Unit	Condition
A5	460	465	nm	I _f =20mA
A6	465	470		
A7	470	475		

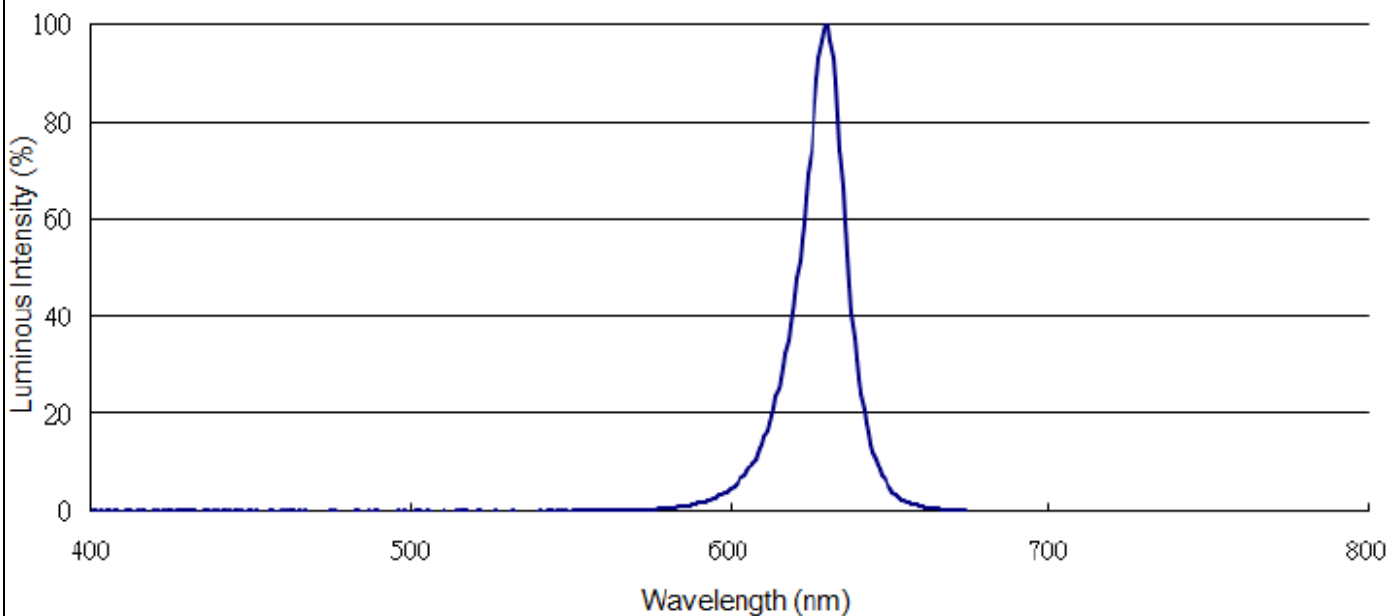
Note:

Tolerance of Dominant Wavelength: ±1nm.

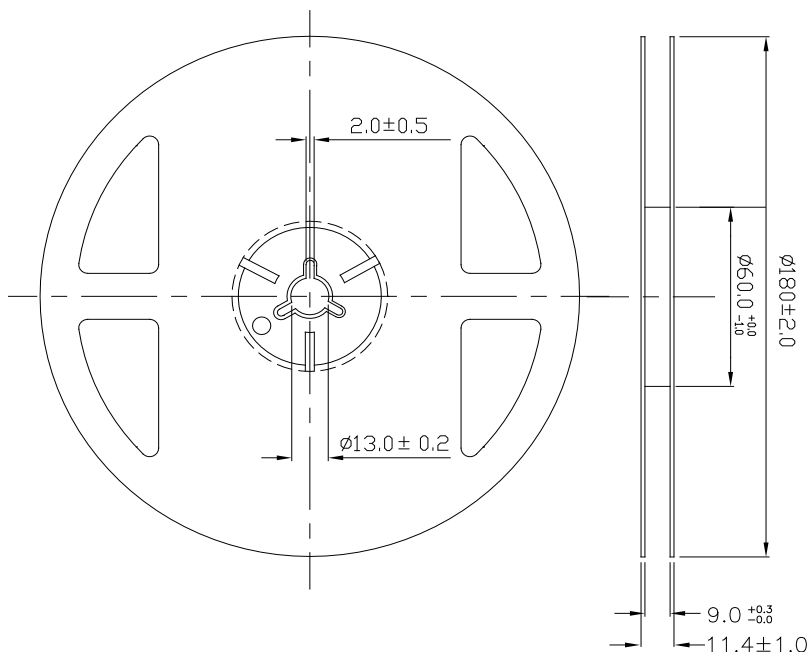
Spectrum Distribution(LB)



Spectrum Distribution(JE)



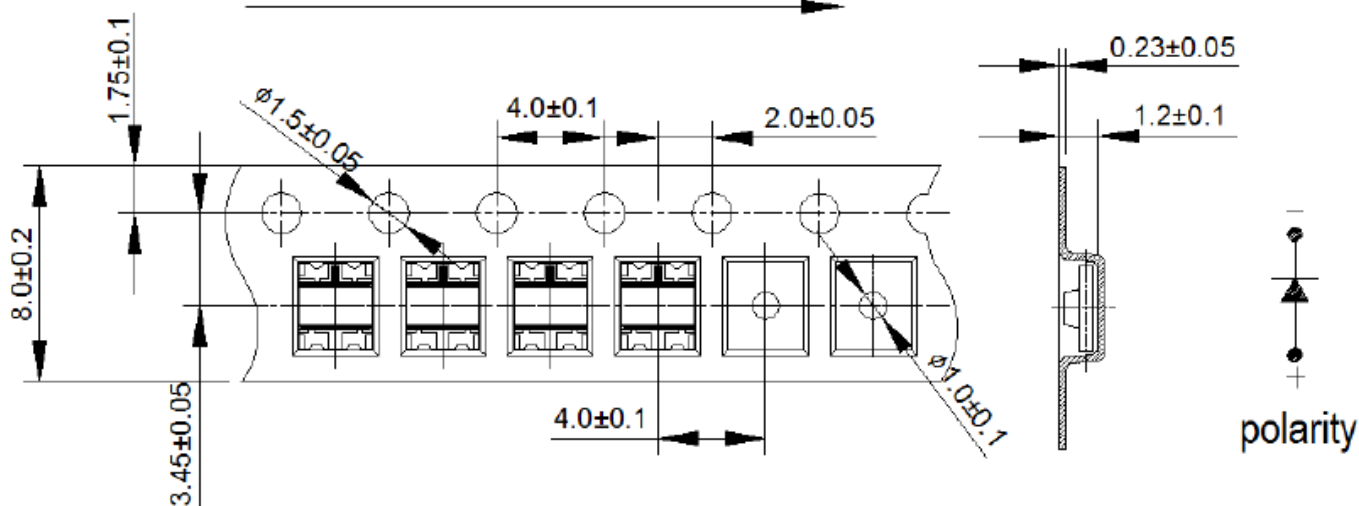
Reel Dimensions



Note:
Tolerances unless mentioned ± 0.1 mm, Unit = mm

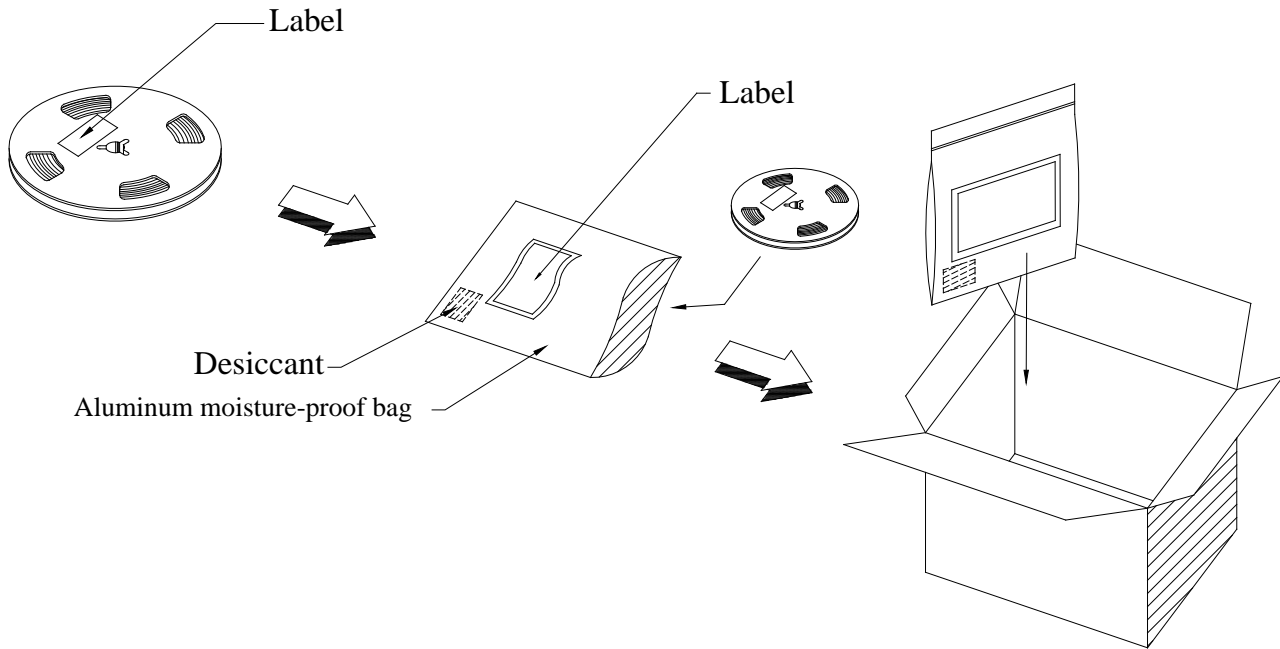
Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel

Progressive direction \rightarrow



Note:
1. Tolerance unless mentioned is ± 0.1 mm, Unit = mm.
2. Minimum packing amount is 1000 pcs per reel.
3. Maximum packing amount is 2000 pcs per reel.

Moisture Resistant Packing Process



Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C/10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
4	High Temperature/Humidity Reverse Bias	Ta=85°C,85%RH	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Ta=-40°C	1000 Hrs.	22 PCS.	0/1
6	High Temperature Storage	Ta=100°C	1000 Hrs.	22 PCS.	0/1
7	DC Operation Life	Ta=25°C, If = 20 mA	1000 Hrs.	22 PCS.	0/1

Precautions for Use

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

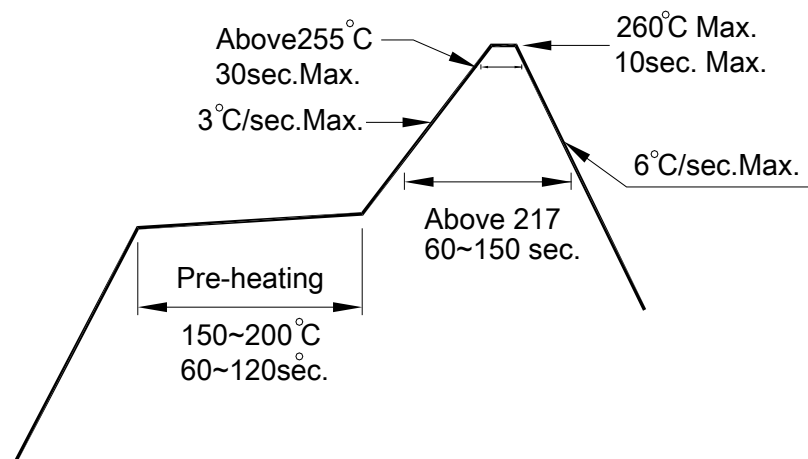
2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.